

Small-sized Class-D Speaker Amplifiers

Analog Input Monaural Class-D Speaker Amplifier



No.10101EAT06

Description

BD5466GUL

BD5466GUL is a monaural Class-D speaker amplifier that contained ALC function for mobile phone, portable type electronic devices etc. LC filter of speaker output is not needed, can form monaural speaker amplifier. with 3 external parts. ALC, short for Automatic Level Control, is a function that automatically adjusts up to the level of suppression of distortion (clip) of output wave form during excessive input. The time until the limit release operation of output level is called the release time (or recovery time). This IC adopts high-speed release time (4ms/1dB Typ.) and suits the application which repeats big volume in the short time such as the camera shutter sound.

Through Class-D operation, efficiency is high low power consumption, that is why it's suitable for battery drive application. The current consumption during shutdown when lowered to $0.01\mu A(Typ.)$, from the shutdown to the operation time is early and at the same time pop sound is few that is why its also suitable in repeating active and shutdown.

Feature

- 1) Contains Digital ALC (Automatic Level Control) Function
- 2) External Parts: 3points
- 3) Ultra slim type package: 9pin WL-CSP(1.7×1.7×0.55mmMax.)
- BD5460/61GUL (No ALC Function, Gain Fixed Goods) Pin Compatible Specs BD5465/67/68GUL (ALC Function, Gain Fixed Goods) Pin Compatible Specs
- 5) Maximum Gain: 18dB(Typ.) [during ALC operation, 18~3dB@1dB Step]
- 6) ALC high speed release(recovery) time: 4ms/1dB(Typ.)
- 7) Limit output power $\,$: 0.7W (Typ.) [VDD=4.2V, RL=8 Ω , THD+N \leqq 1%]
 - : 0.5W (Typ.) [VDD=3.6V, RL=8 Ω , THD+N≤1%]
- 8) Audio Analog Input (corresponds to single-end input / differential input)
- 9) Output LC filter free
- 10) Pop noise suppression circuit
- 11) Shutdown Function (use as mute at the same time) [low shutdown current = 0.01µA (Typ.)]
- 12) Contains protection circuit: output short, thermal shutdown, under voltage lockout (UVLO)

Applications

Mobile phone, Portable audio device, PND, DSC, Note-PC etc.

Absolute Maximum Rating(Ta=+25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	VDDmax PVDDmax	7.0	V
Power Dissipation	Pd	690*	mW
Storage Temperature Range	Tstg	-55 ~ +150	°C
SDNB Pin Input Range	V _{SDNB}	-0.3~VDD+0.3	V
IN+, IN- Pin Input Range	V _{IN}	-0.3~VDD+0.3	V

In case Ta=+25°C or more, 5.52 mW decrease per 1°C When mounting Rohm Typical Board 50.0mmx58.0mm (Material: Glass Epoxy)

Operation Range

Parameter	Symbol	Range	Unit
Temperature	Topr	-40 ~ +85	°C
Power Supply Voltage	VDD PVDD	+2.5 ~ +5.5	V
Common Mode Input Voltage Range	V _{IC}	+0.5 ~ VDD-0.8	V

This product is not designed for protection against radioactive rays.

● Electrical Characteristic (Ta=+25°C, VDD=+3.6V, Unless specified otherwise)

Parameter		Cumbal		Limits		Unit	Conditions
		Symbol	Min.	Тур.	Max.		
<all device=""></all>							
Circuit current (no signa	ıl)	Icc	_	3	6	mA	IC Active, No Load V _{SDNB} =VDD
Circuit current (shutdow	n)	I _{SDN}	_	0.01	2	μA	IC Shutdown V _{SDNB} =GND
<audio feature=""></audio>							
Limit output power		Po	0.035 ×VDD ²	0.044 ×VDD ² 2	0.055 ×VDD ²	W	BTL, f=1kHz, R _L =8Ω THD+N≦1% , *1
Total harmonic distortio	n	T _{HD+N}	_	0.2	1	%	BTL, fin=1kHz, R_L =8 Ω P_O =0.3W , *1
Maximum Gain		G _{MAX}	17	18	19	dB	BTL, *1
ALC Limit level		V_{LIM}	1.5 ×VDD	1.68 ×VDD	1.89 ×VDD	Vpp	BTL, *1
ALC Release level		V_{REL}	1.19 ×VDD	1.34 ×VDD	1.5 ×VDD	Vpp	BTL, *1
Switching frequency		fosc	150	250	350	kHz	
Start-up time		T _{ON}	0.73	1.02	1.71	msec	
Audio input resistance		Ri	22	33.5	45	kΩ	Gain=18dB
<control terminal=""></control>	<control terminal=""></control>						
SDNB terminal	Н	V _{SDNBH}	1.4	_	VDD	V	IC Active
Threshold voltage	L	V _{SDNBL}	0	_	0.4	V	IC Shutdown
SDNB terminal	Н	I _{SDBNH}	12	24	36	μA	V _{SDNB} =3.6V
Inflow Current	L	I _{SDNBL}	-5	_	5	μA	V _{SDNB} =0V

^{*1} Filter bandwidth for measurement: 400~30kHz, LC filter for AC measurement: L=22µH / C=1µF, BTL: Voltage between A3,C3

Shutdown control

• Onataowii control		
Control terminal	Conditions	
SDNB	Conditions	
Н	IC operation (active)	
L	IC stop (shutdown)	

•ALC Parameter

ALC Parameter				
Attack Time (Typ.)	Release Time(Typ.)	Gain Switch Step (Typ.)		
~1ms/1dB @ fin=100Hz ~0.5ms/1dB @ fin=1kHz ~0.05ms/1dB @ fin=10kHz	4ms/1dB @ fin=100∼10kHz	±1dB		

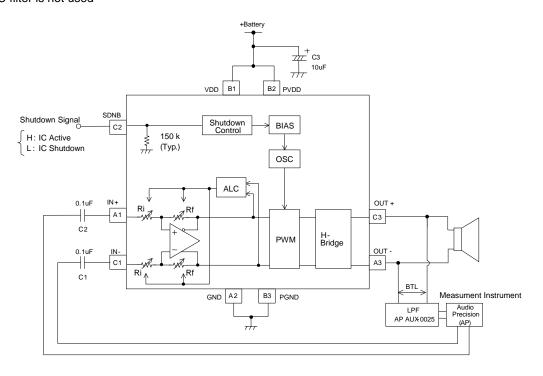
The gain switch timing during ALC operation occurs at zero cross point of audio output voltage. For that, attack time, release time will change at input frequency "fin". ALC Parameter is fixed. ALC operation doesn't correspond to noise of impulse.

BD5466GUL Technical Note

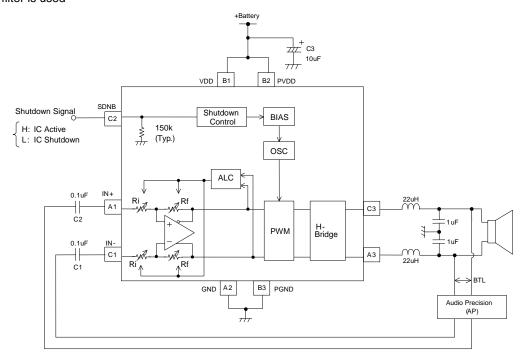
Measurement Circuit Diagram

<Audio Characteristics Method of Evaluation >

■In case LC filter is not used



■In case LC filter is used



Audio characteristics can be measured to insert LC filter between output pin and speaker load, if you don't have measurement equipment for switching amplifier, like AUX-0025, Audio Precision.

Arrange the LC filter directly close to output pin.

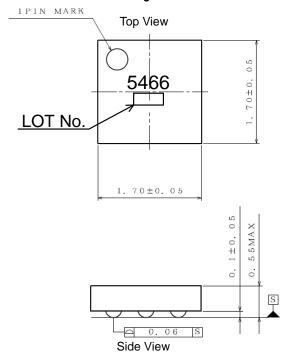
In case of L=22 μ H, C=1 μ F, cut off frequency becomes:

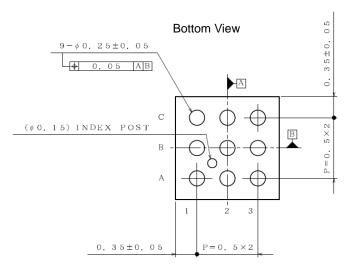
$$fc = \frac{1}{2\pi\sqrt{LC}} = \frac{1}{2\pi\sqrt{22\mu\,H\!\times\!1\!\mu F}} \cong 34kHz$$

For Inductor L, please use huge current type.

(Reference)TDK: SLF12575T-220M4R0

External Dimension Diagram

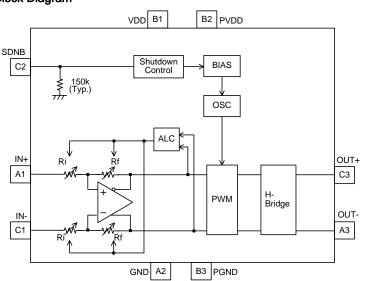




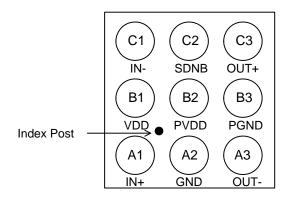
9pin WL-CSP(VCSP50L1) [1.7 × 1.7 × 0.55mm Max, 0.5mm Pitch]

(Unit: mm)

Block Diagram



●Pin Arrangement (Bottom View)



●Pin Explanation

Pin No.	Pin Name	Explanation	
A1	IN+	Audio differential input + terminal	
A2	GND	GND terminal (signal)	
A3	OUT-	Class-D BTL output - terminal	
B1	VDD	VDD terminal (signal)	
B2	PVDD	VDD terminal (power)	
В3	PGND	GND terminal (power)	
C1	IN-	Audio differential input - terminal	
C2	SDNB	Shutdown control terminal	
C3	OUT+	Class-D BTL output + terminal	

BD5466GUL Technical Note

Application circuit example

SHORT the power supply pin VDD (B1), PVDD (B2) at board pattern, then use singleness power supply.

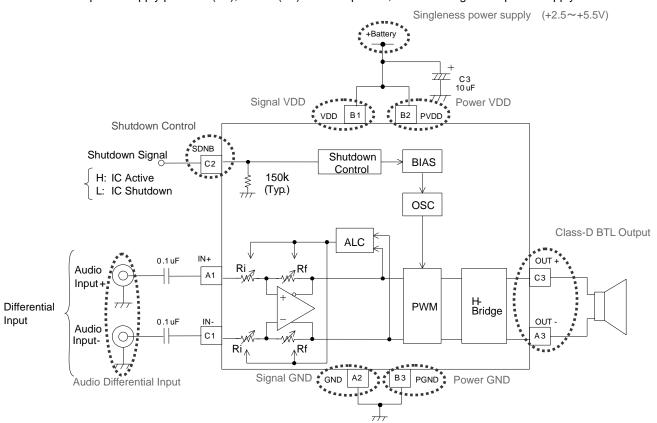


Fig1. Differential Input(With Input Coupling Capacitor)

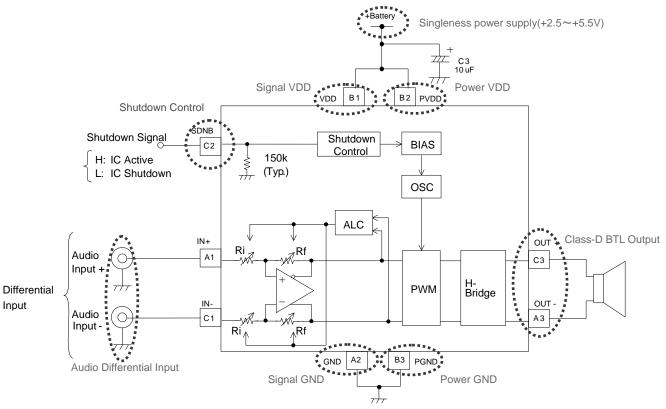


Fig2. Differential Input(Without Input Coupling Capacitor)

BD5466GUL Technical Note

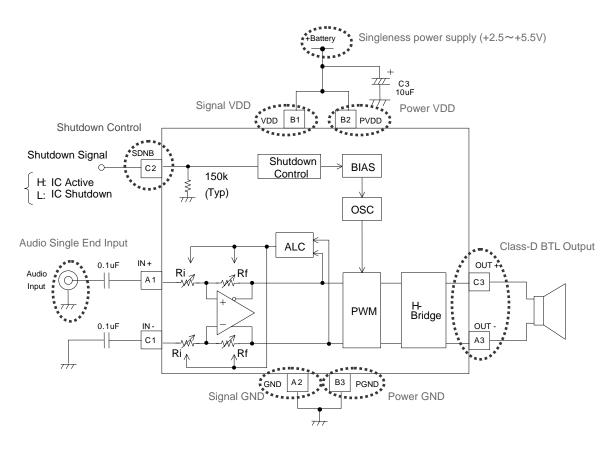


Fig3. Single end input (during IN+ input)

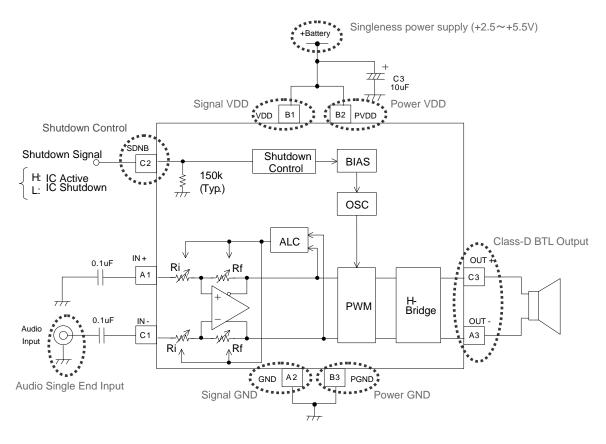


Fig4. Single end input (during IN-Input)

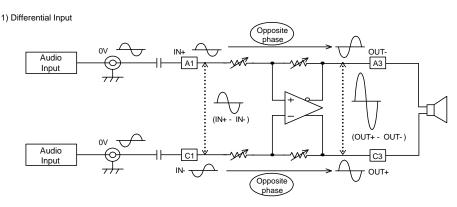
● About the difference of differential input and single end input

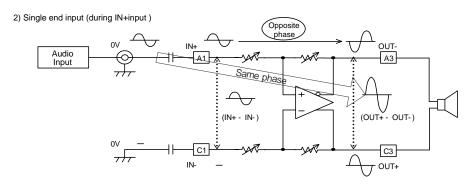
• BD5466GUL uses full differential amplifier.

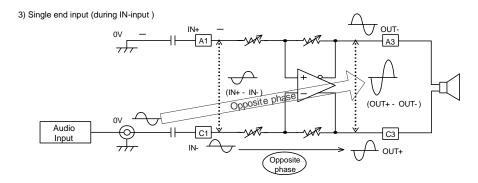
BD5466GUL is a Class-D but, in relation to Audio Input and Output, is same with the conventional Class-AB Amplifier.

For simplicity purposes of the diagram, the Class-D amplifier output stage is omitted in the following explanation.

About the resistor, signal — on the diagram Gives meaning to changes of gain setting by means of ALC Control.







OAbout single end input

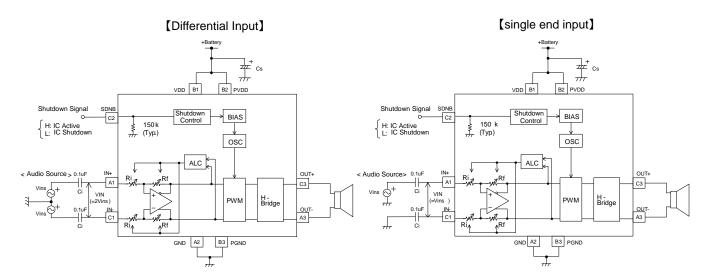
- Input is possible whether IN+ or IN- Pin.

 Don't make input pin open, through the input coupling capacitor, please connect to GND as seen on the example above.

 Audio input pin should make "mute" condition, not "open" condition when you don't input any signal.
- During single end input IN+ and IN-, there is a difference with the phase relation of input and output.
 Because of differential amplifier, if input (IN+ IN-), output(OUT+ OUT-), the audio input and output phase relation will become:

Phase	IN+ Input	IN- Input
Audio Input ⇒ output (OUT+ - OUT-)	Same phase	Opposite phase

OGain calculation



When Input Level is calculated at IC typical and audio source typical, when input coupling capacitor (Ci) value is large enough, every gain during the differential input and single end input will become:

Typical Input Level	Differential Output	Single End Output	
IC	Formula①		
Audio Source	Formula ²	Formula①	

1.IC reference(Difference Input, Single End Input): Formula ①

VIN means the Input Voltage between IC Input Pin (IN+, IN-), VOUT means the output voltage between IC Output Pin (OUT+, OUT-). During differential input and single end input, the gain calculation formula at IC reference which includes ALC operation is written below:

2. Audio Source reference (Differential Input): Formula 2

When the input level of audio source is Vins, the relation with the input voltage VIN between IC input pin is written below:

$$Vins = VIN / 2$$

During differential input, at audio source reference that includes ALC operation, gain calculation formula will become:

3. Audio Source reference (Single End Input): Formula ①

When the Input level of audio source is Vins, the relation with input voltage VIN between IC input pin (IN+,IN-) becomes:

$$Vins = VIN$$

During single end input, at the audio source that includes ALC operation, gain calculation formula becomes:

Audio Input Pin External LPF connection example

■External LPF connection example

The connection example of 1^{st} -order LPF which is formed at Resistor R_{LPF} and Capacitor C_{LPF}, to the Audio Input Pin IN+/- (A1, C1 Pin) is shown below. The cut frequency of input LPF, together with the single end input and differential input is written below:

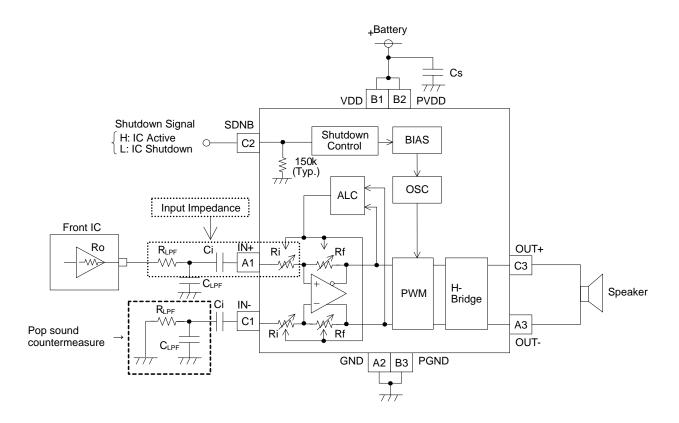
 $fc_{LPF} = 1 / (2 \times \pi \times R_{LPF} \times C_{LPF})$ [Hz]

Ex) $f_{CLPF}=10kHz \Rightarrow C_{LPF}=0.01\mu F, R_{LPF}=1.59k\Omega$

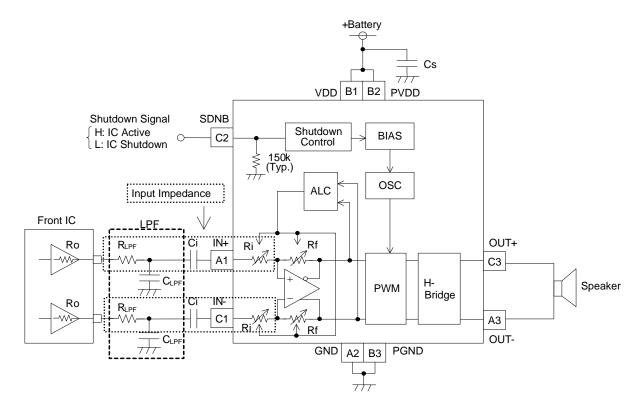
1) During single end input

When LPF is connected to audio input pin at single end input setting, at start-up characteristics of audio input pin IN+/-, during start-up with unbalance (power supply ON/OFF, or shutdown ON/OFF), there is a risk that POP sound will occur so please be careful.

When no audio input, and in order to prevent output noise, please make previous IC "mute" condition, not "open" condition. Please refer at the same time to POP Sound countermeasure example.



2) Differential Input



■Caution during External LPF Setting

External LPF Resistor R_{LPF} which is composed of IC input resistor Ri, forms input impedance. The bigger the resistor value of LPF resistor R_{LPF} the more it will decrease the gain.

When the input capacitor Ci has enough large capacity value, the relation among external LPF resistor R_{LPF} and IC input resistor Ri and Gain will become:

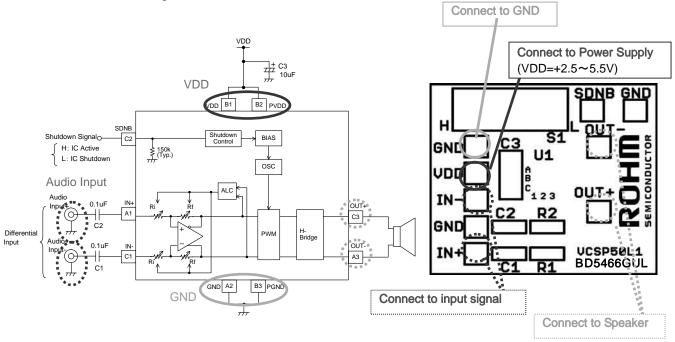
$$Gain = 20 \times log | Rf / (Ri + R_{LPF}) | [dB]$$

Input resistor Ri of BD5466GUL and resistor value of feedback resistor Rf will become the following below, during ALC operation, changes at ±1dB step, and becomes 16 stages switch specs.

- #15. Ri=116k Ω (Typ.), Rf=184k Ω (Typ.)@Gain=4dB #16. Ri=124k Ω (Typ.), Rf=176k Ω (Typ.)@Gain=3dB

Also with the driver ability of previous IC step, after checking, constant setting of external LPF and Resistor R_{LPF}.

● Evaluation Board Circuit Diagram



**Power Supply terminals VDD(B1), PVDD(B2) are SHORT in the board pattern and use a single power.

Evaluation Board Parts List

Qty.	Item	Description	SMD Size	Manufacturer/ Part Number
2	C1, C2	Capacitor, 0.1μF	0603	Murata GRM188R71C104KA01D
1	C3	Capacitor, 10µF	A (3216)	ROHM TCFGA1A106M8R
1	S1	Slide Switch	4mm X 10.2mm	NKK SS-12SDP2
1	U1	IC, BD5466GUL, Mono Class-D Audio Amplifier	1.7mm X 1.7mm WLCSP Package	ROHM BD5466GUL
1	PCB1	Printed-Circuit Board, BD5466GUL EVM	_	_

About the external part

①Input coupling capacitor (C1, C2)

Input coupling capacitor is 0.1µF.

Input impedance during maximum gain 18dB is $33.5k\Omega$ (Typ.). A high-pass filter is composed by the input coupling capacitor and the input impedance.

Cut-off frequency"fc" by the formula below, through input coupling capacitor C1(=C2) and input impedance Ri.

$$fc = \frac{1}{2\pi \times Ri \times C1}[Hz]$$

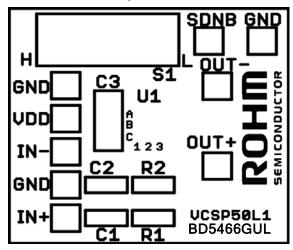
In case of Ri=33.5k Ω , C1(=C2)=0.1 μ F, cut-off frequency is about 48Hz

2 Power Supply Decoupling Capacitor (C3)

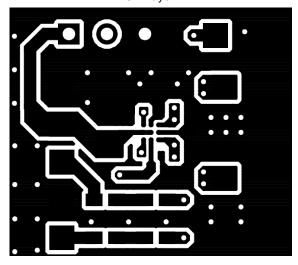
Power Supply Decoupling Capacitor is 10uF. When the capacity value of Power Supply Decoupling Capacitor is made small, it will have an influence to the audio characteristics. When making it small, be careful with the audio characteristics at actual application. ESR (equivalent series resistor) is low enough; please use capacitor with capacity value of $1\mu F$ or more.

●Evaluation Board PCB Layer

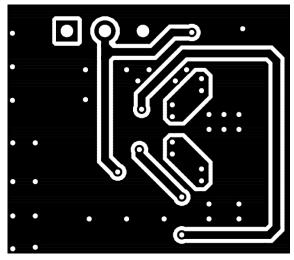
TOP Layer Silk Pattern



TOP Layer



Bottom Layer



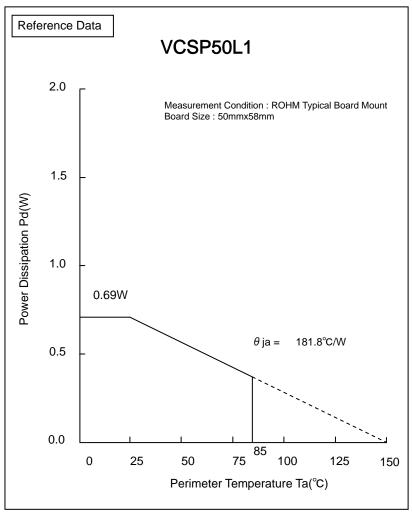
About IC Thermal Design

The IC Characteristics has a big relation with the temperature that will be used, to exceed the maximum tolerance junction temperature, can deteriorate and destroy it. Instant destruction and long-time operation, from these 2 standpoints, there is a need to be careful with regards to IC thermal. Please be careful with the next points.

The absolute maximum rating of IC shows the maximum junction temperature (Tjmax.) or the operation temperature range (Topr), so refer to this value, use Pd-Ta characteristics (Thermal reduction ratio curve). If input signal is excessive at a state where heat radiation is not sufficient, there will be TSD(Thermal Shutdown)

For TSD, the chip temperature operates at around 180°C, releases if its around 120°C or less. Since the aim is to prevent damage on the chip, please be careful because the long use time at the vicinity where TSD operates can deteriorate the dependency of the IC.

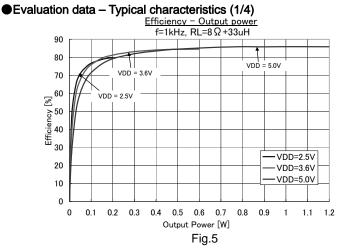
Thermal Reduction Ratio Curve

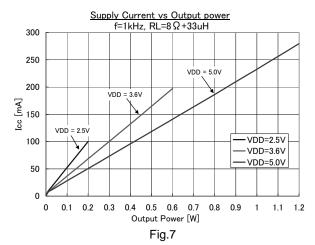


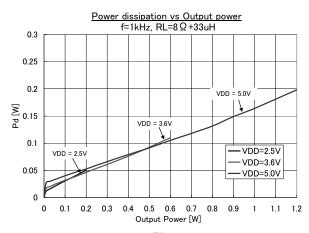
Note: This value is the real measurement, but not the guaranteed value.

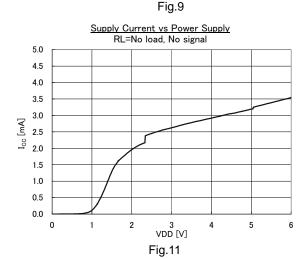
The value of power dissipation changes based on the board that will be mounted.

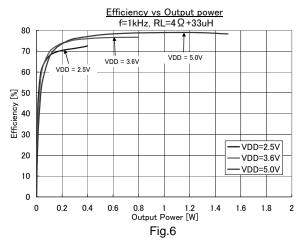
The power dissipation of main IC during the heat dissipation design of many mounted boards, will become bigger than the value of the above graph.

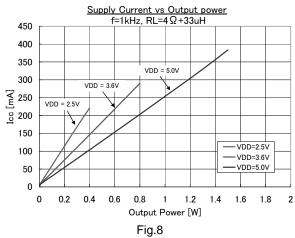


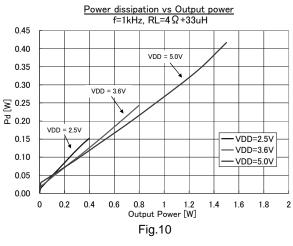


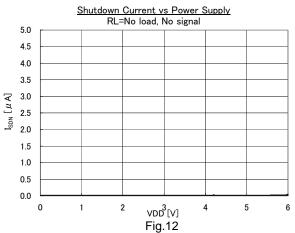












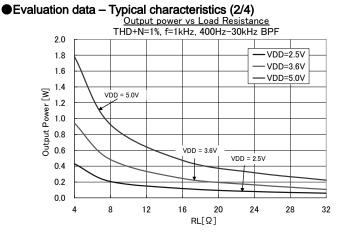
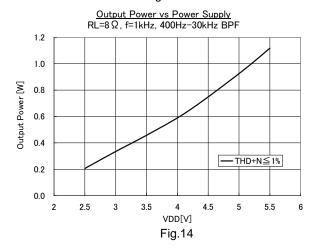
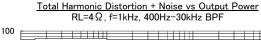


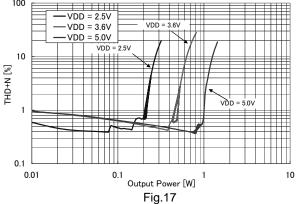
Fig.13

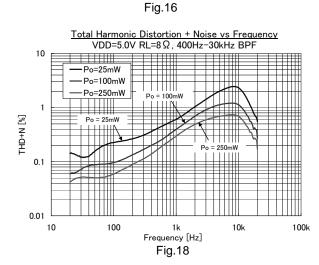


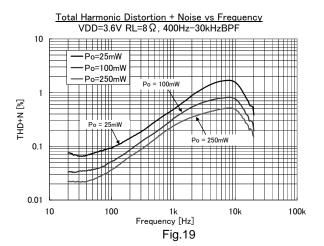
Output Power vs Power Supply RL=4 Ω , f=1kHz, 400Hz-30kHz BPF 2.5 2.0 Output Power [W] 1.5 1.0 THD+N≦1% 0.5 0.0 2 2.5 3 5 5.5 6 VDD[V] Fig.15

 $\frac{\text{Total Harmonic Distortion + Noise vs Output Power}}{\text{RL=8}\,\Omega,\,\text{f=1kHz},\,400\text{Hz-30kHz BPF}}$ 100 VDD = 2.5V VDD = 3.6V VDD = 5.0V VDD = 3.6V 10 THD+N [%] 0.1 0.01 10 Output Power [W]



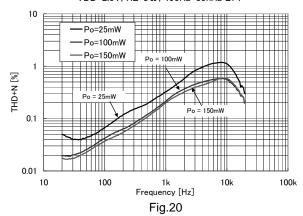


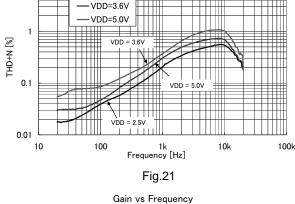




● Evaluation data – Typical characteristics (3/4)

Total Harmonic Distortion + Noise vs Frequency VDD=2.5V, RL=8 Ω, 400Hz-30kHz BPF

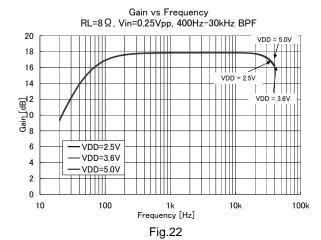


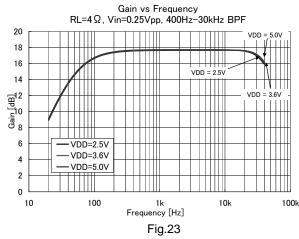


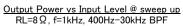
VDD=2.5V

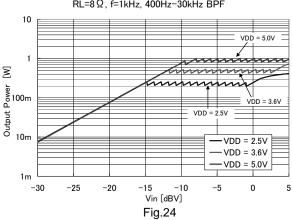
Total Harmonic Distortion + Noise vs Frequency RL=8 Ω, Po=125mW, 400Hz-30kHz BPF

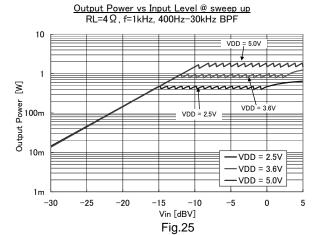
10











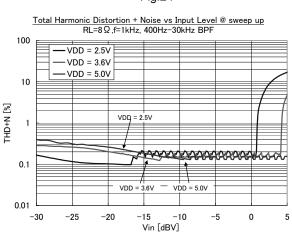
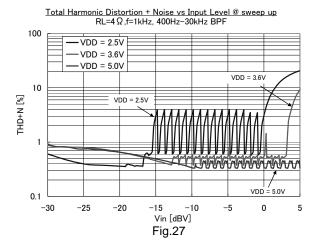
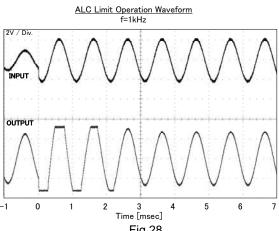
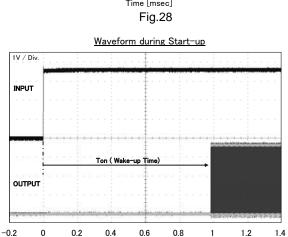


Fig.26

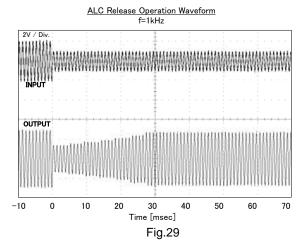


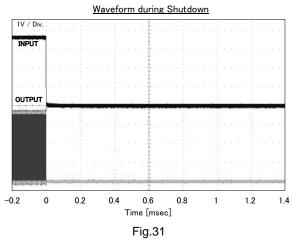
●Evaluation data – Typical characteristics (4/4)





Time [msec] Fig.30





Notes for use

- (1) The numerical value and the data of the mention are a design representative value and are not the one which guarantees the value.
- (2) It is convinced that it should recommend application circuit example but in case of use, we request the confirmation of the characteristic more sufficiently. When changing an external part fixed number and becoming use, it considers sprawl of the external part and our company's LSI including the transition characteristic in addition to the stillness characteristic and so on, see and fix an enough margin.
- (3) Absolute maximum ratings

This IC may be damaged if the absolute maximum ratings for the applied voltage, temperature range, or other parameters are exceeded. Therefore, avoid using a voltage or temperature that exceeds the absolute maximum ratings. If it is possible that absolute maximum ratings will be exceeded, use fuses or other physical safety measures and determine ways to avoid exceeding the IC's absolute maximum ratings.

- (4) GND terminal's potential
 - Try to set the minimum voltage for GND terminal's potential, regardless of the operation mode.
- (5) Shorting between pins and mounting errors

When mounting the IC chip on a board, be very careful to set the chip's orientation and position precisely. When the power is turned on, the IC may be damaged if it is not mounted correctly. The IC may also be damaged if a short occurs (due to a foreign object, etc.) between two pins, between a pin and the power supply, or between a pin and the GND.

- (6) Operation in strong magnetic fields
 - Note with caution that operation faults may occur when this IC operates in a strong magnetic field.
- (7) Thermal design

Ensure sufficient margins to the thermal design by taking in to account the allowable power dissipation during actual use modes, because this IC is power amplifier. When excessive signal inputs which the heat dissipation is insufficient condition, it is possible that thermal shutdown circuit is active.

- (8) Thermal shutdown circuit
 - This product is provided with a built-in thermal shutdown circuit. When the thermal shutdown circuit operates, the output transistors are placed under open status. The thermal shutdown circuit is primarily intended to shut down the IC avoiding thermal runaway under abnormal conditions with a chip temperature exceeding T_{jmax} =+150°C, and is not intended to protect and secure an electrical appliance.
- (9) Load of the output terminal

This IC corresponds to dynamic speaker load, and doesn't correspond to the load except for dynamic speakers. When using speaker load 8Ω or less (especially 4Ω), there will be a risk of generating distortion at the speaker output wave form during ALC limit operation.

(10) The short protection of the output terminal

This IC is built in the short protection for a protection of output transistors. When the short protection is operated, output terminal become Hi-Z condition and is stopped with latch. Once output is stopped with latch, output does not recover automatically by canceling the short-circuiting condition. The condition of stopping with latch is cancelled, when power supply or mute signal is turned off and turned on again.

- (11) Operation Range
 - The rated operating power supply voltage range (VDD=+2.5V~+5.5V) and the rated operating temperature range (Ta=-40°C~+85°C) are the range by which basic circuit functions is operated. Characteristics and rated output power are not guaranteed in all power supply voltage ranges or temperature ranges.
- (12) Electrical Characteristics

Every audio characteristics list of the limit output power, total harmonic distortion, maximum gain, ALC limit level, ALC release level etc. shows the typical characteristics of the device, highly dependent to the board lay-out, parts to be used, power supply. The value when the device and each component are directly mounted to the board of Rohm.

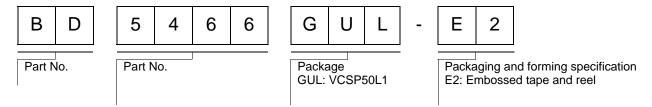
(13) Power Supply

Since the Power Supply Pin for signal (VDD) and power supply for Power (PVDD) is SHORT at internal, short the board pattern, then use a single power supply. Also, the power supply line of class-D speaker amplifier flows big peak energy. It will influence the audio characteristics based on the capacity value of power supply decoupling capacitor, arrangement. For the power supply decoupling capacitor, please arrange appropriately the low capacity (1µF or more) of ESR (equivalent series resistor) directly near to IC Pin.

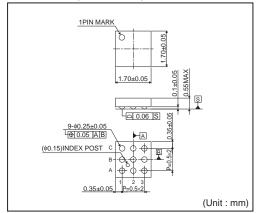
(14) ALC (Automatic Level Control) Function

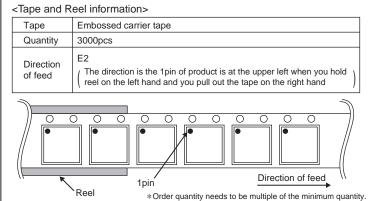
The ALC automatically adjusts the audio output level, and a function that prevents the over output to the speaker. When ALC function is working, gain switches at zero-cross point of audio output normally. If the time that audio output reaches to zero-cross point is long, gain switches at about 1msec later (attack time), at about 25msec later (release time). So, attack time and release time will change at audio input frequency. ALC parameter is fixed. The system does not correspond to noise of impulse. Also, ALC limit control will become a power supply tracking type, limit output power is dependent to power supply voltage. The ALC characteristics of limit output power, ALC limit and release limit will be influenced by the shaking so please be careful.

Ordering part number



VCSP50L1(BD5466GUL)





Notice

Precaution on using ROHM Products

Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁP	AN	USA	EU	CHINA
CLAS	SSⅢ	CLASSIII	CLASS II b	CL ACCIII
CLAS	SSIV		CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Notice - GE © 2014 ROHM Co., Ltd. All rights reserved.

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

Precaution Regarding Intellectual Property Rights

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:
- 2. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the information contained in this document.

Other Precaution

- 1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

Notice - GE © 2014 ROHM Co., Ltd. All rights reserved.

General Precaution

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
- 3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

Notice – WE © 2014 ROHM Co., Ltd. All rights reserved.